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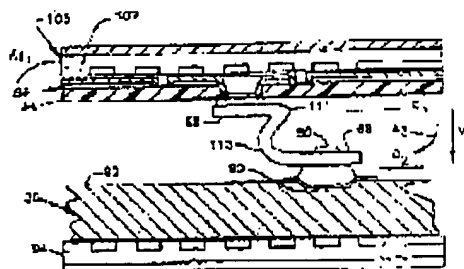
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(54) MOUNTING STRUCTURE OF MICROELECTRONIC ELEMENT AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a high-performance connecting part for microelectronics.

SOLUTION: A connecting part is provided with an insulating sheet (first element) 34 carrying a plurality of leads arranged on the surface of the sheet 34 in the form of a surface array. Each lead 60 has a terminal-side end section 66 fixed to the sheet 34 and a front-side end section 68 which can be separated from the sheet 34. The front-side end section 68 of the lead 60 is attached to another insulating sheet 34, a semiconductor wafer (second element), etc. The leads 60 are deformed in bent shapes having heights in the vertical direction by relatively moving the first and second elements against each other. When the connecting parts are used, a semiconductor chip assembly can be constituted. The assembly is composed of a plurality of contacts arranged on a chip in the form of a surface array, a plurality of terminals which are arranged on the insulating sheet 34 in the form of a surface array, and a plurality of S-shaped metallic ribbons which respectively connect the terminals to the contacts. It is possible to provide an easily deformable insulating material around the leads 60 between the sheet 34 and the chip.



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